



ASM-CX700/ETX

Fanless Advanced Slim Machine



Features

- Onboard VIA Eden ULV V4 500 MHz up to 1.5 GHz CPU
- VIA CX700M Chipset Support MPEG-2/4 and WMV9 Video Acceleration
- One SODIMM up to 1 GB DDR2 SDRAM
- 1 Mini PCI, 1 Type I/II CF
- 1 COM, 4 USB
- Optional DVI output, TV-out, Dual GigaLAN, 2 W Amplifier
- 4 LED indicators for Power, HDD, LAN 1 & LAN 2 (optional)
- Supports 2.5" SATA / IDE HDD / USB WiFi Module
- Super Slim Size: 182 x 257 x 25 mm

MPEG-2/4

25mm High

GigaLAN

4 USB

Fanless

VESA

Specifications

System (ASM-CX700)

• CPU	Onboard VIA Eden ULV V4 500 MHz up to 1.5 GHz
• BIOS	Award 512 KB Flash BIOS
• System Chipset	VIA CX700M
• I/O Chip	VIA VT1211
• System Memory	One 200-pin SODIMM supports up to 1 GB DDR2 400/533 SDRAM
• SSD	One CF socket by IDE secondary slave channel supports Type I/II Compact Flash Card
• Watchdog Timer	Reset: 1~255 min. and 1 min./step
• Display	VIA CX700M
• Audio	VIA V71708 supports 5.1-CH Audio
• Ethernet	Realtek RTL8100C 10/100 Base-T Fast Ethernet controllers; Optional Dual RTL8110S GigaLAN
• System Indicators	4 LED indicators show Power, HDD, LAN 1 & LAN 2
• Drive Bay	Mounting kit for one 2.5" IDE / SATA HDD (hidden)
• Expansion Interface	1 Mini PCI (hidden)

External I/O

• Serial Port	1 x RS-232
• LAN Port	1 x RJ-45, optional dual GigaLAN
• VGA/LCD Port	1 x DB-15, 1 x DVI (optional)
• TV Port	1 x RCA jack (optional)
• Audio Port	Mic in, Line in, Line out
• USB Port	4 x USB 2.0
• Mouse & K/B	1 x PS/2 mini DIN (share with optional LAN2)

Power Supply Unit

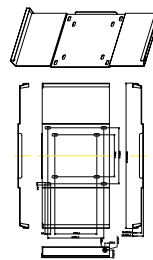
• Power Input	100 ~ 240 Vdc / 50 ~ 60 Hz
• Power Output	+12 Vdc / 4.16 A (50 W)

Environment & Mechanical

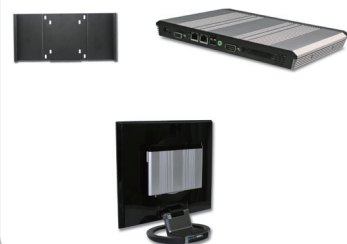
• Power Input	100~240 Vac / 50~60 Hz
• Power Output	+12 Vdc / 4.16 A (50 W)
• Power Requirement	+12 V @ 1.35 A (with VIA Eden 1 GHz & 1 GB DDR2 667 SDRAM), +12 V @ 0.97 A (with VIA Eden 500 MHz & 1 GB DDR2 667 SDRAM)

• Operating Temperature	-10~60°C (32~104°F)
• Storage Temperature	-20~+75°C (-4~167°F)
• Relative Humidity	5 to 90% @ 40°C (104°F), relative humidity, non-condensing
• Dimension (W x D x H)	7.2" x 10.1" x 1.0" (182 x 257 x 25 mm)
• Weight	3.3 lbs (1.5 kg)
• Mounting	Desktop (VESA Compliance)

VESA kit for ASM-CX700



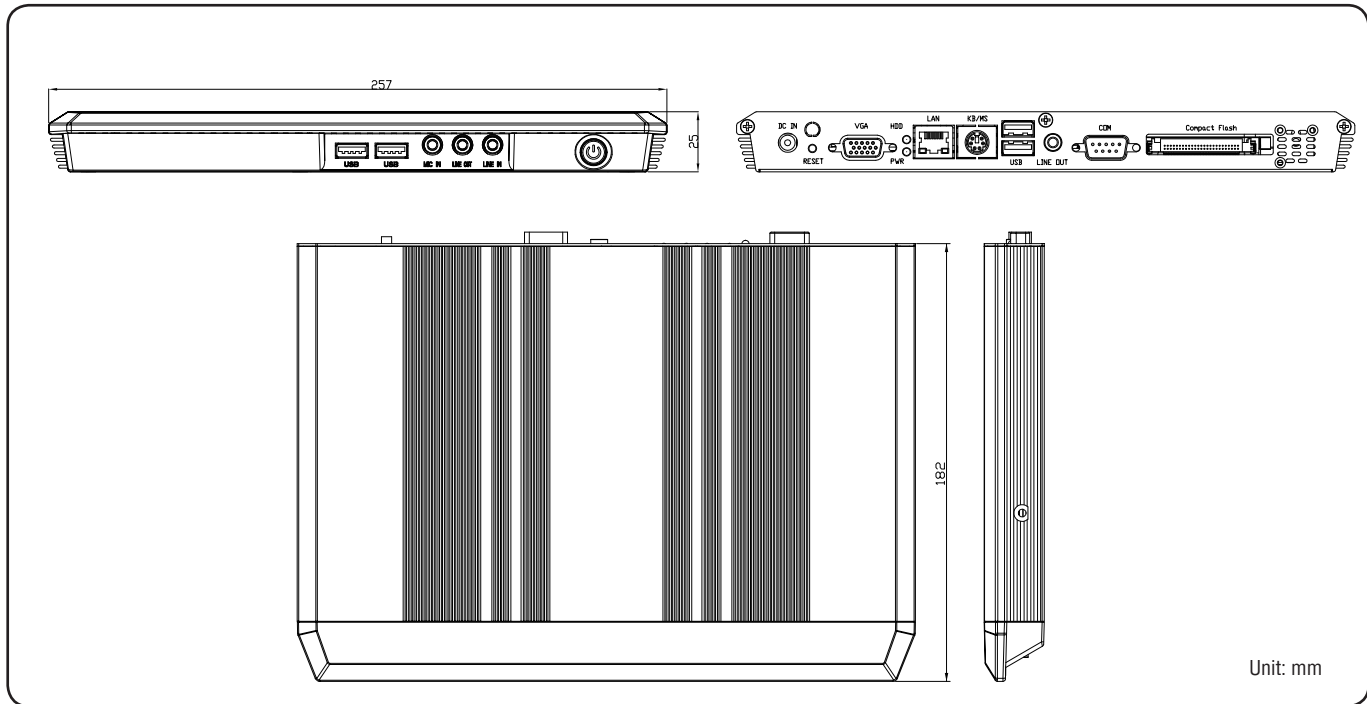
ASM-CX700 with VESA Mount



Ordering Information

- **ASM-CX700-E05**
VIA Eden ULV 500 MHz advanced slim machine with VGA, LAN, COM, 4 USB, CF, Mini PCI
- **ASM-CX700-E10**
VIA Eden ULV 1 GHz advanced slim machine with VGA, 2 Giga LAN, COM, 4 USB, CF, Mini PCI
- **EBM-CX700**
5.25" VIA Eden ULV 500 MHz Mini Module with VGA, 5.1-CH Audio, LAN, COM, 4 USB, CF, Mini PCI, 2 SATA and GPIO
- **ACC-ASM-VESA-1R**
ASM series LCD VESA kit (RoHS)
- **ACC-CF-xx**
CompactFlash Card Series (xx = Capacity, Capacity Option: 128, 256, 512 MB, 1, 2, 4 GB)
- **ACC-MEM-XXX-03R**
DDR2 200-pin Memory Series (xx = Capacity, Capacity Option: 256, 512 MB, 1 GB)

Diagram



CH1
ETX/
COM Express

CH2
3.5" SBC

CH3
EPIC

CH4
5.25" SBC

CH5
PC/104

CH6
IMB

CH7
Embedded
System

CH8
MTP
Panel PC

CH9
Panel PC

CH10
ahis

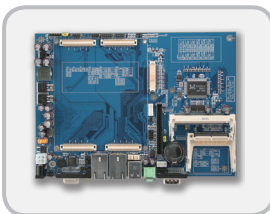
CH11
Peripheral

CH12
Index

ASM-ETX Series- ETX Module for Options

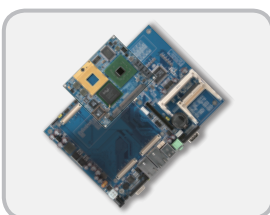
Changeable CPU Core

ASM-ETX Series adopts ETX Computer-on-Module technology that enables scalable system upgradeability by separating the CPU core module and I/O interfaces into two various boards. ASM-ETX series therefore can easily be upgraded by simply replacing a next-generation higher speed ETX core module while without changing the carrier board. This modular designed Micro PC can accommodate any Avalue ETX core module to meet different project requirements.



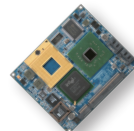
EAP-EX52 ETX Carrier Board P. 1-19

- 5.25" Single Board Computer form Factor
- Accepts Avalue's & 3rd party's ETX CPU Module
- VGA / LVDS / Audio / TV-out Interface
- 1 Mini PCI, 1 Type I/II CF, 2 COM, 4 USB
- 1 LAN or 2 GigaLAN



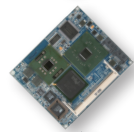
COM standards for Computer-On-Module. Avalue's COMs are complete-like system boards with complete PC Functionality that plug into application-specific baseboards through high-density, low profile, surface-mount connectors. COMs are also scalable and interchangeable, and deliver rapid development of semi-custom solutions for embedded applications.

ETX Module



ESM-945ETX P.1-10

- Supports Intel® Core™ Duo / Core™ 2 Duo CPU
- Intel® 945GME / ICH7-M Chipset
- Dual View, Dual LVDS
- Audio, LAN, ISA Bus



ESM-910ETX P.1-11

- Supports Intel® 910GME Celeron® M CPU
- Intel® 910GME/ICH6-M Chipset
- Dual View, Dual LVDS
- Audio, LAN, ISA Bus



ESM-2743 P.1-13

- Supports Intel® 852GM Celeron® M CPU
- Intel® 852GM/ICH4 Chipset
- Dual View, Dual LVDS
- Audio, LAN, ISA Bus



ESM-2740 P.1-12

- Supports Intel® 855GME Pentium® M/Celeron® M CPU
- Intel® 855GME/ICH4 Chipset
- Dual View, Dual LVDS
- Audio, TV-out, LAN, ISA Bus



ESM-2545 P.1-15

- Supports AMD Geode LX800 @ 0.9W CPU
- AMD Geode LX800/CS5536 Chipset
- Dual View, TFT, LVDS
- Audio, LAN, ISA Bus